



Flash Memory Summit



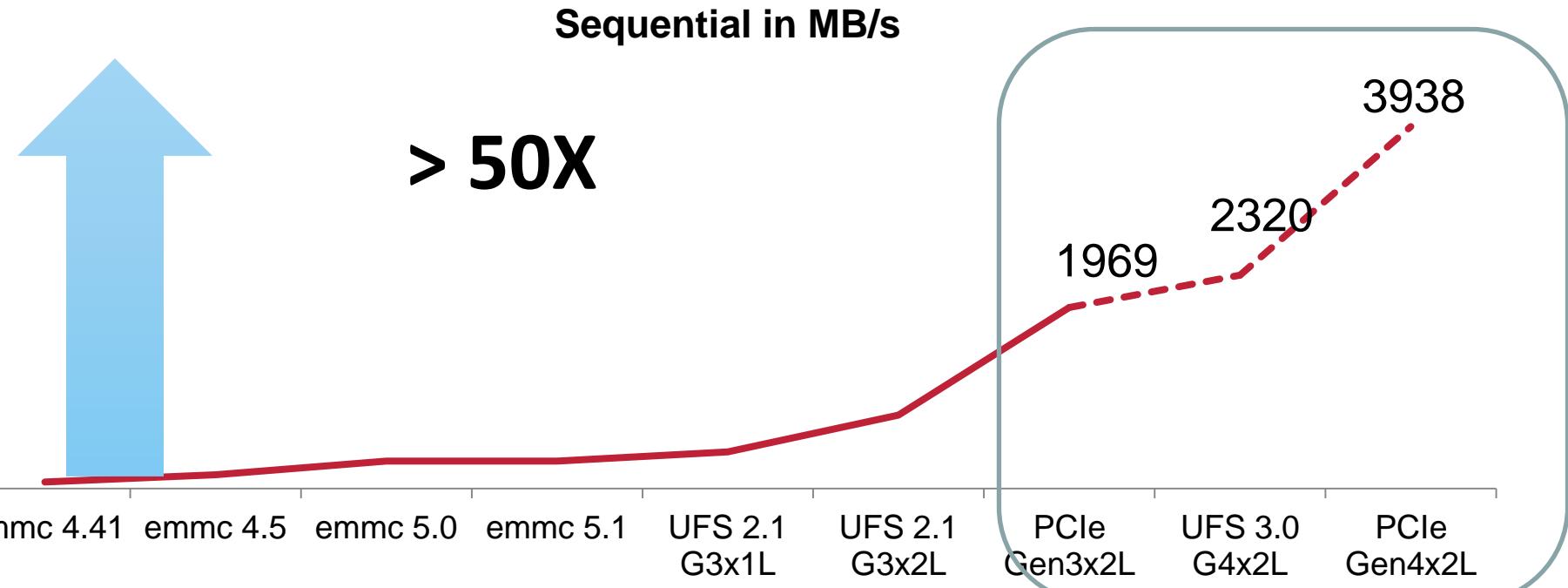
# New Technologies and New Standards Enable New Mobile Applications

**Robert Hsieh**  
**Silicon Motion, Inc.**



Flash Memory Summit

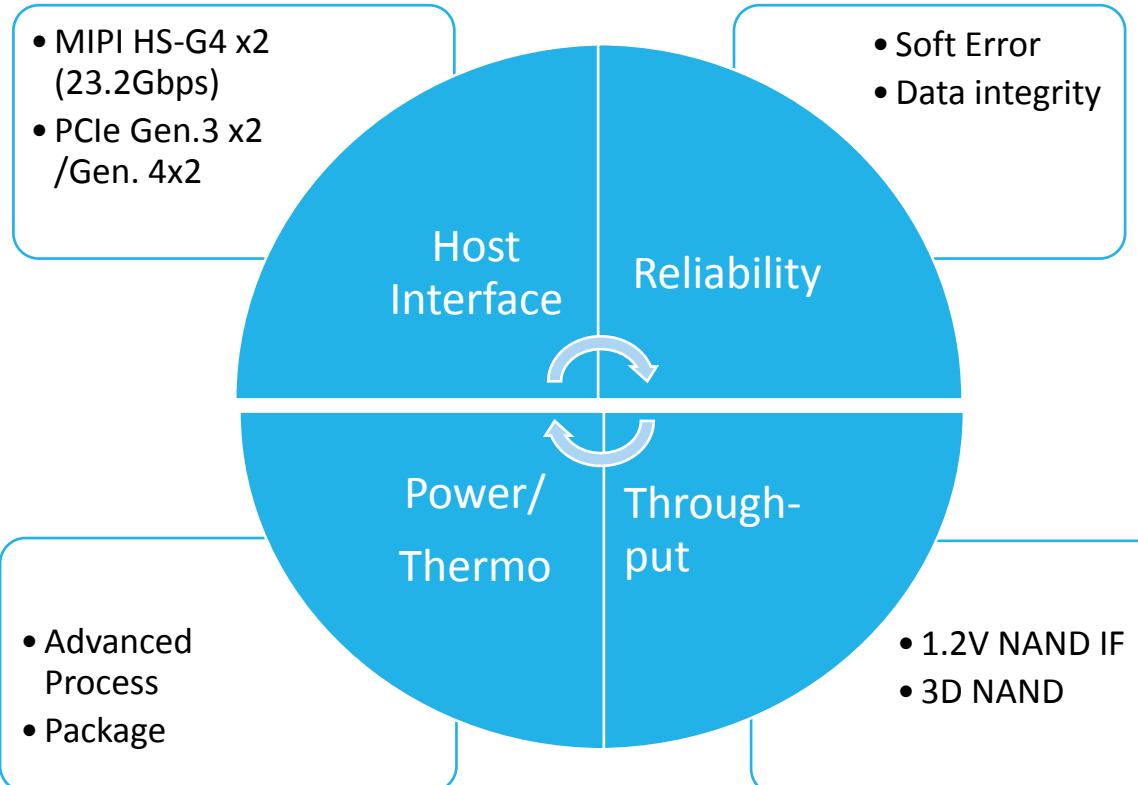
# Mobile Storage Performance





Flash Memory Summit

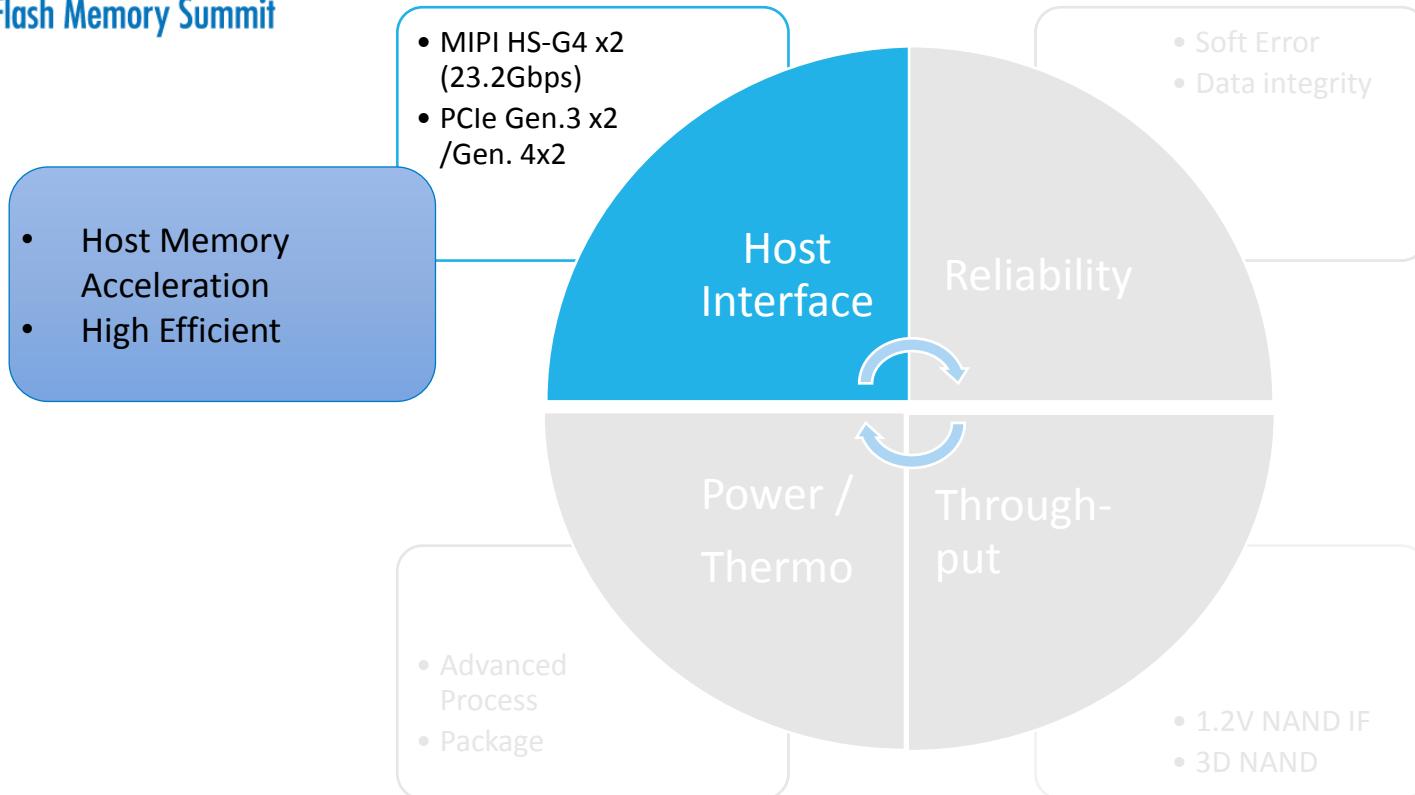
# Next Generation Mobile Storage Controller





Flash Memory Summit

# Next Generation Mobile Storage Controller





Flash Memory Summit

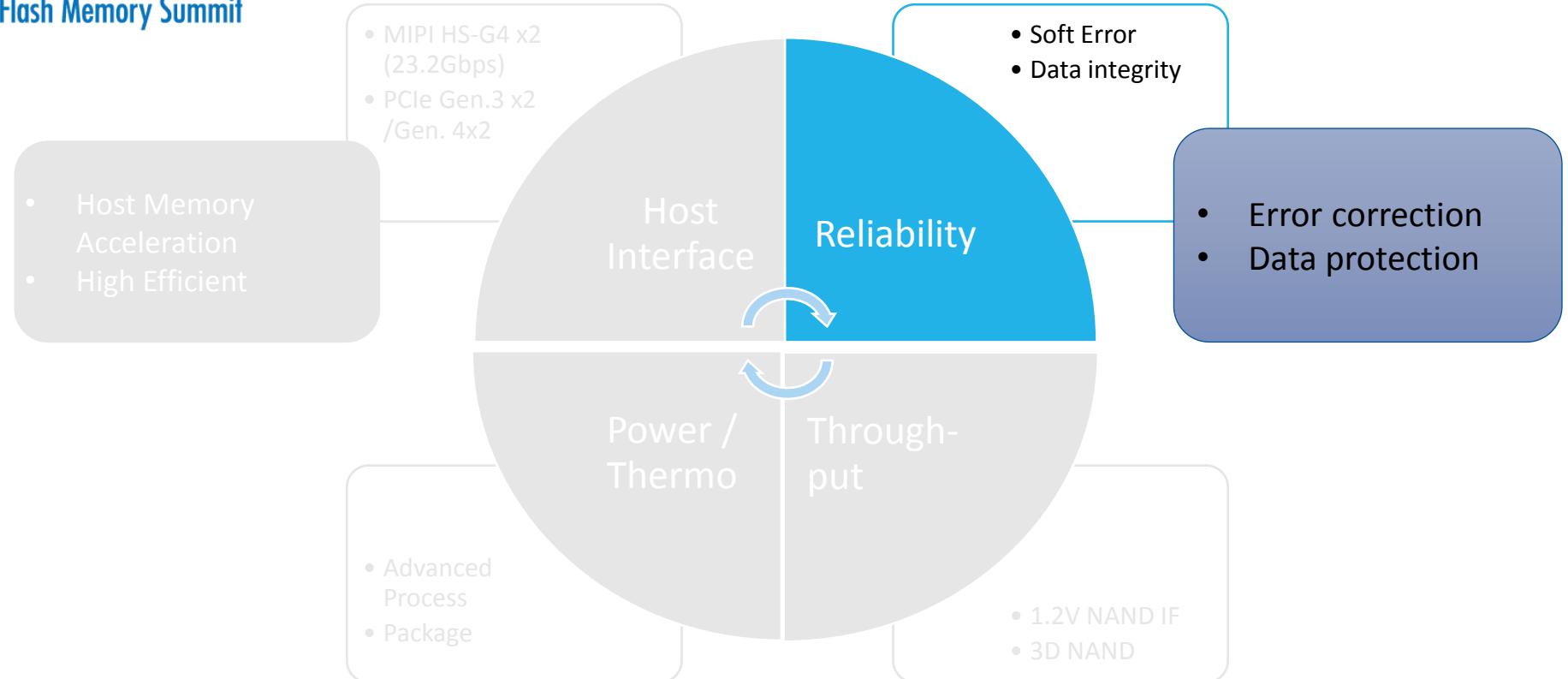
# Host Interface

- Utilize Host Memory to reduce the table update
- Advanced Line coding (128b/130b)



# Next Generation Mobile Storage Controller

Flash Memory Summit





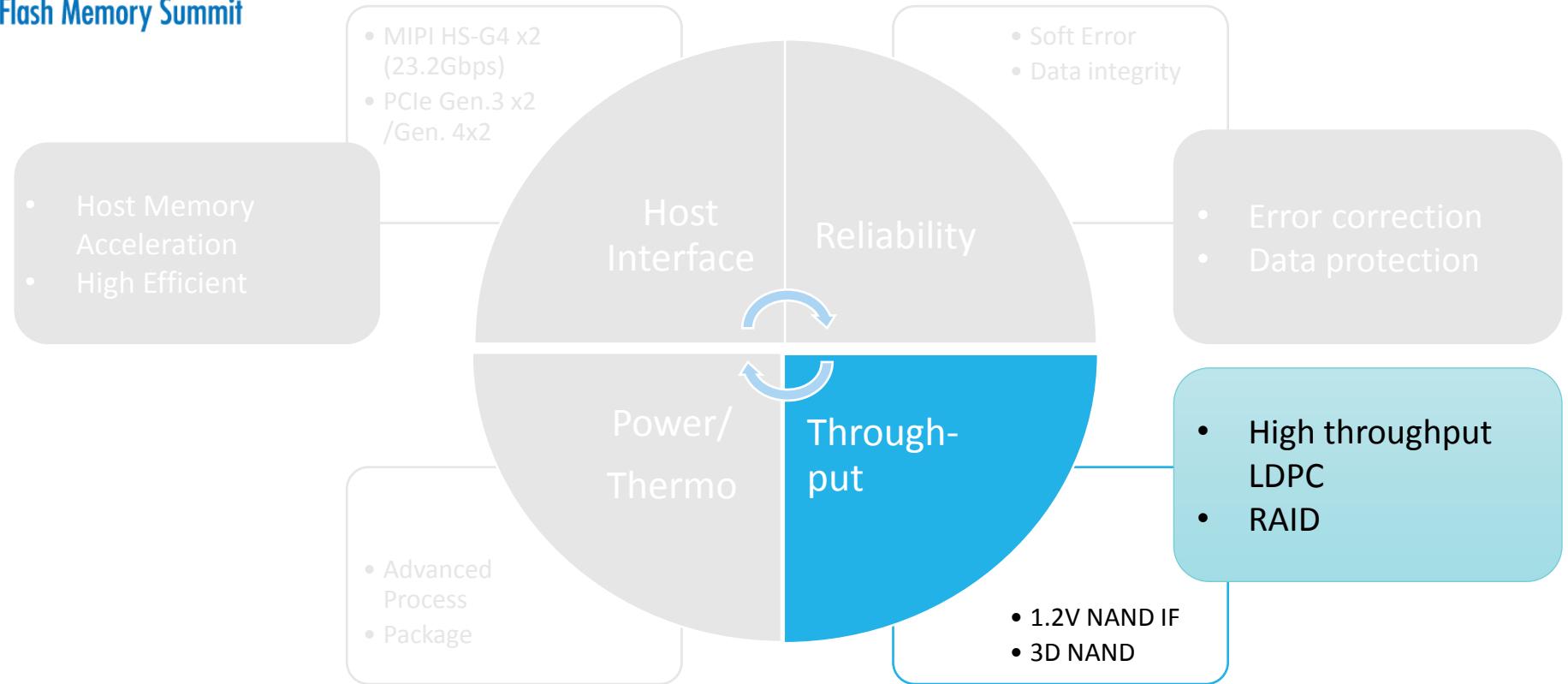
# Reliability

- More Soft bit error due to large SRAM density
- Error correction to prevent potential stuck
- Data protection/encryption



# Next Generation Mobile Storage Controller

Flash Memory Summit





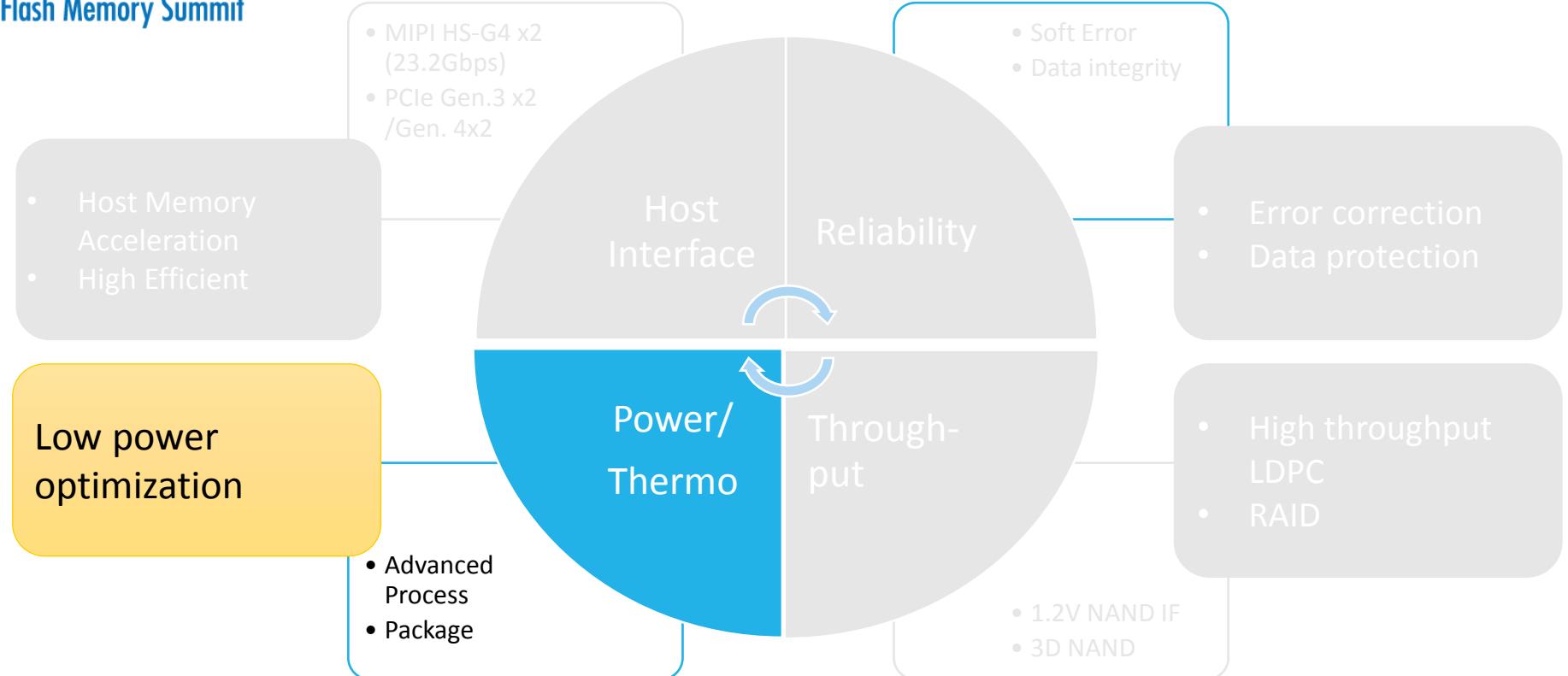
## Performance/Throughput

- **1.2V 3D NAND can support 1200MT/s above**
- **2KB/4KB LDPC is expected for high throughput and higher performance**
- **Multi-core CPU**



# Next Generation Mobile Storage Controller

Flash Memory Summit





Flash Memory Summit

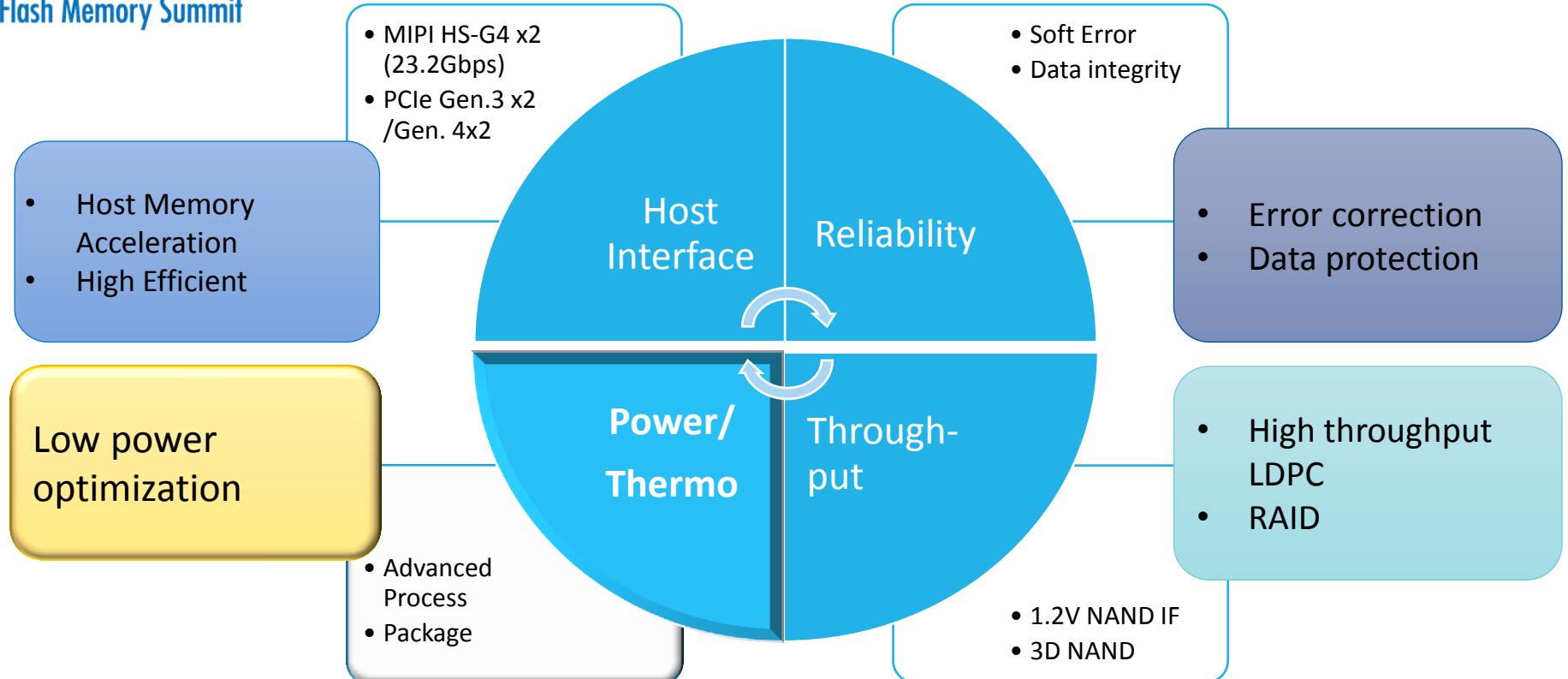
# Power Consumption/Thermo

- Advanced process with superior low leakage
- SRAM, Logic cell (SVT, HVT cell)
- Wire-bonding vs Flip-chip



Flash Memory Summit

# Next Generation Mobile Storage Controller





# Summary

- **Optimize the design of PCIe PHY/NVMe**
- **Consider the design trade-off between performance and power consumption**
- **PCIe/UFS3.x aim for Mobile computing and Automotive applications**



Flash Memory Summit

Visit us at the Booth 413

Thank you

[robert.hsieh@silicomotion.com](mailto:robert.hsieh@silicomotion.com)